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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/546,620	08/23/2005	Takashi Kariya	276730US90PCT	4465
22850	7590	04/14/2010		
OBLON, SPIVAK, MCCLELLAND MAIER & NEUSTADT, L.L.P. 1940 DUKE STREET ALEXANDRIA, VA 22314				
EXAMINER				
DINH, TUAN T				
ART UNIT		PAPER NUMBER		
2841				
NOTIFICATION DATE		DELIVERY MODE		
04/14/2010		ELECTRONIC		

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

patentdocket@oblon.com  
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### Office Action Summary

**Application No.**

10/546,620

**Applicant(s)**

KARIYA ET AL.

**Examiner**

Tuan T. Dinh

**Art Unit**

2841

**Period for Reply** -- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 15 March 2010.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 1,3,4,6-8,11,12 and 18-20 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1,3,4,6-8,11,12 and 18-20 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

**Priority under 35 U.S.C. § 119**

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some \* c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB06)  
Paper No(s)/Mail Date \_\_\_\_\_
- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date \_\_\_\_\_
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: \_\_\_\_\_

### **DETAILED ACTION**

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 03/15/10 has been entered.

### ***Claim Rejections - 35 USC § 103***

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

2. Claims 1-4, 7-8, 11, 18-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sakamoto et al. (cited in the record) in view of Jones et al. (U.S. Patent 5,541,450).

As to claim 1, Sakamoto et al. discloses a multi-layer printed wiring board as shown in figure 1 comprising:

a first substrate (12, 11b) having an opening (15) and a plurality of terminals (pads or wirings/lands on top surface of substrate 12, 11b),

a second substrate (11a, 12) laminated to the first substrate (12, 11b) having a plurality of terminals (the pads or lands on a bottom surface of the substrate 12) and

having a metallic layer portion (electrodes 22) positioned in the opening (15) of the first substrate (12, 11b), and a plurality of non-through holes (see figure 1) filled with conductive materials (14) and electrically connected to the metallic layer portion (22), a carrier board (16) having terminals (21) formed in the opening and connected to the metallic layer portion (22) of the second substrate (11a).

Sakamoto does not specific disclose an IC having a terminal side and a non-terminal side opposite to the terminal side formed in the opening of the metallic layer such that the metallic layer and non-through holes of the second substrate being irradiate heat generated by the IC component.

Jones shows a BGA semiconductor package (30) as shown in figure 2 comprising a first substrate (31) having an opening (33) loaded with an IC (18) having a terminal side and a non-terminal side opposite to the terminal side having terminals (22) formed on top surface of the IC (18), the IC (18) formed on a metallic layer portion (36, see column 3, line 34).

It would have been obvious to one having ordinary skill in the art at the time was made to have a teaching of Jones employed in the wiring board of Sakamoto et al. in order to form a multi-electronic/chip package.

Regarding claims 3-4, Sakamoto et al. as modified by Jones discloses in figure 1 that the external terminals of the first substrate (12, 11b) disposed offset the external terminals of the second substrate (11a), the first substrate having a plurality of conductive non-through holes (14) connected to the external terminals (top surface of layer 12) and the second substrate having a plurality of conductive non-through holes

(14) connected to the external terminals of the second substrate (bottom surface of the bottom layer 12), the conductive non through holes (14) of the first and second substrates are offset each other, see figure 1.

Regarding claims 7-8, 11, Sakamoto et al. as modified by Jones discloses a plurality of bonding pads (37) capable of being rectangular shape of the first substrate provided for the IC (18) having wire bond (44) connected on the pads (37) and the through holes (39) formed underneath of the pads.

It would have been obvious to one having ordinary skill in the art at the time was made to have a teaching of Jones employed in the wiring board of Sakamoto et al. in order to provide an electrical connection.

Regarding claim 18, Sakamoto et al. as modified by Jones that discloses the terminals of the first substrate (12, 11b) are position in a peripheral form surrounding the IC component, and the terminals (14) of the second substrate (11a, 12) are position in a grid form (LGA).

Regarding claims 19-20, Sakamoto as modified by Jones that discloses the IC component (18) has a bottom portion of which an entire surface of the bottom portion of the IC component is loaded over the metallic layer portion (36) of Jones in the second substrate, and the first substrate (31) has a plurality of terminals (37, 41) positioned to be connected to the plurality of terminals of the IC component (18) by wire-bonded connected, and the external terminals and terminals in the first substrate are positioned to face the opposite side of the metallic layer portion of the second substrate. It would have been obvious to one having ordinary skill in the art at the time was made to have a

teaching of Jones employed in the wiring board of Sakamoto et al. in order to form a multi-electronic/chip package.

3. Claims 6, 12 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sakamoto et al. in view of Jones as applied to claims above, and further in view of Londa (as in record).

Regarding claims 6, 12, Sakamoto et al. as modified by Jones discloses all of the limitation of the claimed invention except for solder bumps formed on the pads of each of the substrate. Londa teaches a MCM package as shown in figure 2 that comprising solder bump (74, 92) formed on pads of each of the substrate.

It would have been obvious to one having ordinary skill in the art at the time was made to have a teaching of Londa employed in the wiring board of Sakamoto et al. in view of Jones in order to form a BGA package or make an electrical connection.

#### ***Response to Arguments***

4. Applicant's arguments with respect to claims 1-10 have been considered but are moot in view of the new ground(s) of rejection.

Applicant argues:

The combination of Sakamoto in view of Jones fails to disclose "an IC having a terminal side and a non-terminal side opposite to the terminal side formed in the opening on the metallic layer such that the metallic layer and non-through holes of the second substrate being irradiate heat generated by the IC component."

Examiner disagrees. It is clearly show in the Office action that Sakamoto discloses all of the limitations of claim 1 except for an IC having a terminal side and a

non-terminal side opposite to the terminal side formed in the opening on the metallic layer such that the metallic layer and non-through holes of the second substrate being irradiate heat generated by the IC component. Jones shows a semiconductor package in figure 2 that comprising a first substrate (31) having an opening (33) loaded with an IC (18) having a terminal side (a top surface of the IC) and a non-terminal side (a bottom surface) opposite to the terminal side, the IC (18) formed on a metallic layer portion (36, see column 3, line 34), the metallic layer (36) being capable of being act as a heat spreader to dissipate heat or irradiate heat from the IC mounted on the second substrate.

### ***Conclusion***

5. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Takeda and Kohjiro et al. disclose related art.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T. Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Lee Jinhee can be reached on 571-272-1977. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Tuan T Dinh/  
Primary Examiner, Art Unit 2841.